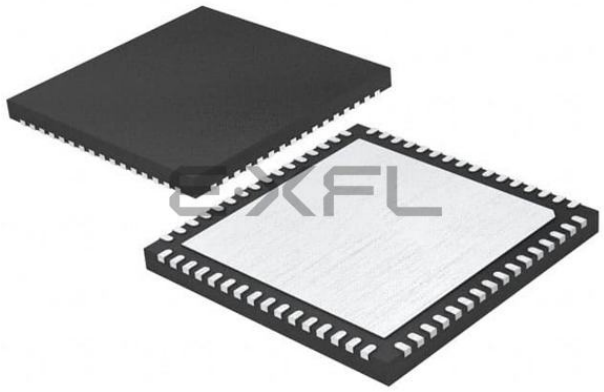
Microchip Technology - PIC32MX320F064H-80I/MR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx320f064h-80i-mr

Pin Diagrams (Continued)

121-Pin XBGA(1)

● = Pins are up to 5V tolerant

PIC32MX440F128L
PIC32MX460F256L
PIC32MX460F512L

	1	2	3	4	5	6	7	8	9	10	11
A	RE4	RE3	RG13	RE0	RG0	RF1	ENVREG	VSS	RD12	RD2	RD1
B	NC	RG15	RE2	RE1	RA7	RF0	VCORE/ VCAP	RD5	RD3	VSS	RC14
C	RE6	VDD	RG12	RG14	RA6	NC	RD7	RD4	VDD	RC13	RD11
D	RC1	RE7	RE5	VSS	VSS	NC	RD6	RD13	RD0	NC	RD10
E	RC4	RC3	RG6	RC2	VDD	RG1	VSS	RA15	RD8	RD9	RA14
F	$\overline{\text{MCLR}}$	RG8	RG9	RG7	VSS	NC	NC	VDD	RC12	VSS	RC15
G	RE8	RE9	RA0	NC	VDD	VSS	VSS	NC	RA5	RA3	RA4
H	RB5	RB4	VSS	VDD	NC	VDD	NC	VBUS	VUSB	RG2	RA2
J	RB3	RB2	RB7	AVDD	RB11	RA1	RB12	NC	NC	RF8	RG3
K	RB1	RB0	RA10	RB8	NC	RF12	RB14	VDD	RD15	RF3	RF2
L	RB6	RA9	AVSS	RB9	RB10	RF13	RB13	RB15	RD14	RF4	RF5

Note 1: Refer to Table 4 for full pin names.

TABLE 4: PIN NAMES: PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES

Pin Number	Full Pin Name
A1	PMD4/RE4
A2	PMD3/RE3
A3	TRD0/RG13
A4	PMD0/RE0
A5	PMD8/RG0
A6	PMD10/RF1
A7	ENVREG
A8	VSS
A9	IC5/PMD12/RD12
A10	OC3/RD2
A11	OC2/RD1
B1	No Connect (NC)
B2	RG15
B3	PMD2/RE2
B4	PMD1/RE1
B5	TRD3/RA7
B6	PMD11/RF0
B7	VCAP/VCORE
B8	PMRD/CN14/RD5
B9	OC4/RD3
B10	VSS
B11	SOSCO/T1CK/CN0/RC14
C1	PMD6/RE6
C2	VDD
C3	TRD1/RG12
C4	TRD2/RG14
C5	TRCLK/RA6
C6	No Connect (NC)
C7	PMD15/CN16/RD7
C8	OC5/PMWR/CN13/RD4
C9	VDD
C10	SOSCI/CN1/RC13
C11	IC4/PMCS1/PMA14/RD11
D1	T2CK/RC1
D2	PMD7/RE7
D3	PMD5/RE5
D4	VSS
D5	VSS
D6	No Connect (NC)
D7	PMD14/CN15/RD6
D8	CN19/PMD13/RD13
D9	SDO1/OC1/INT0/RD0
D10	No Connect (NC)
D11	SCK1/IC3/PMCS2/PMA15/RD10
E1	T5CK/SDI1/RC4
E2	T4CK/RC3
E3	SCK2/PMA5/CN8/RG6
E4	T3CK/RC2
E5	VDD
E6	PMD9/RG1
E7	VSS

Pin Number	Full Pin Name
E8	SDA1/INT4/RA15
E9	RTCC/IC1/RD8
E10	$\overline{SS1}$/IC2/RD9
E11	SCL1/INT3/RA14
F1	$\overline{MCLR}$
F2	SDO2/PMA3/CN10/RG8
F3	$\overline{SS2}$/PMA2/CN11/RG9
F4	SDI2/PMA4/CN9/RG7
F5	VSS
F6	No Connect (NC)
F7	No Connect (NC)
F8	Vdd
F9	OSC1/CLKI/RC12
F10	VSS
F11	OSC2/CLKO/RC15
G1	INT1/RE8
G2	INT2/RE9
G3	TMS/RA0
G4	No Connect (NC)
G5	VDD
G6	VSS
G7	VSS
G8	No Connect (NC)
G9	TDO/RA5
G10	SDA2/RA3
G11	TDI/RA4
H1	AN5/C1IN+/VBUSON/CN7/RB5
H2	AN4/C1IN-/CN6/RB4
H3	VSS
H4	VDD
H5	No Connect (NC)
H6	VDD
H7	No Connect (NC)
H8	VBUS
H9	VUSB
H10	D+/RG2
H11	SCL2/RA2
J1	AN3/C2IN+/CN5/RB3
J2	AN2/C2IN-/CN4/RB2
J3	PGED2/AN7/RB7
J4	AVDD
J5	AN11/PMA12/RB11
J6	TCK/RA1
J7	AN12/PMA11/RB12
J8	No Connect (NC)
J9	No Connect (NC)
J10	U1TX/RF8
J11	D-/RG3
K1	PGEC1/AN1/CN3/RB1
K2	PGED1/AN0/CN2/RB0
K3	VREF+/CVREF+/PMA6/RA10

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An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

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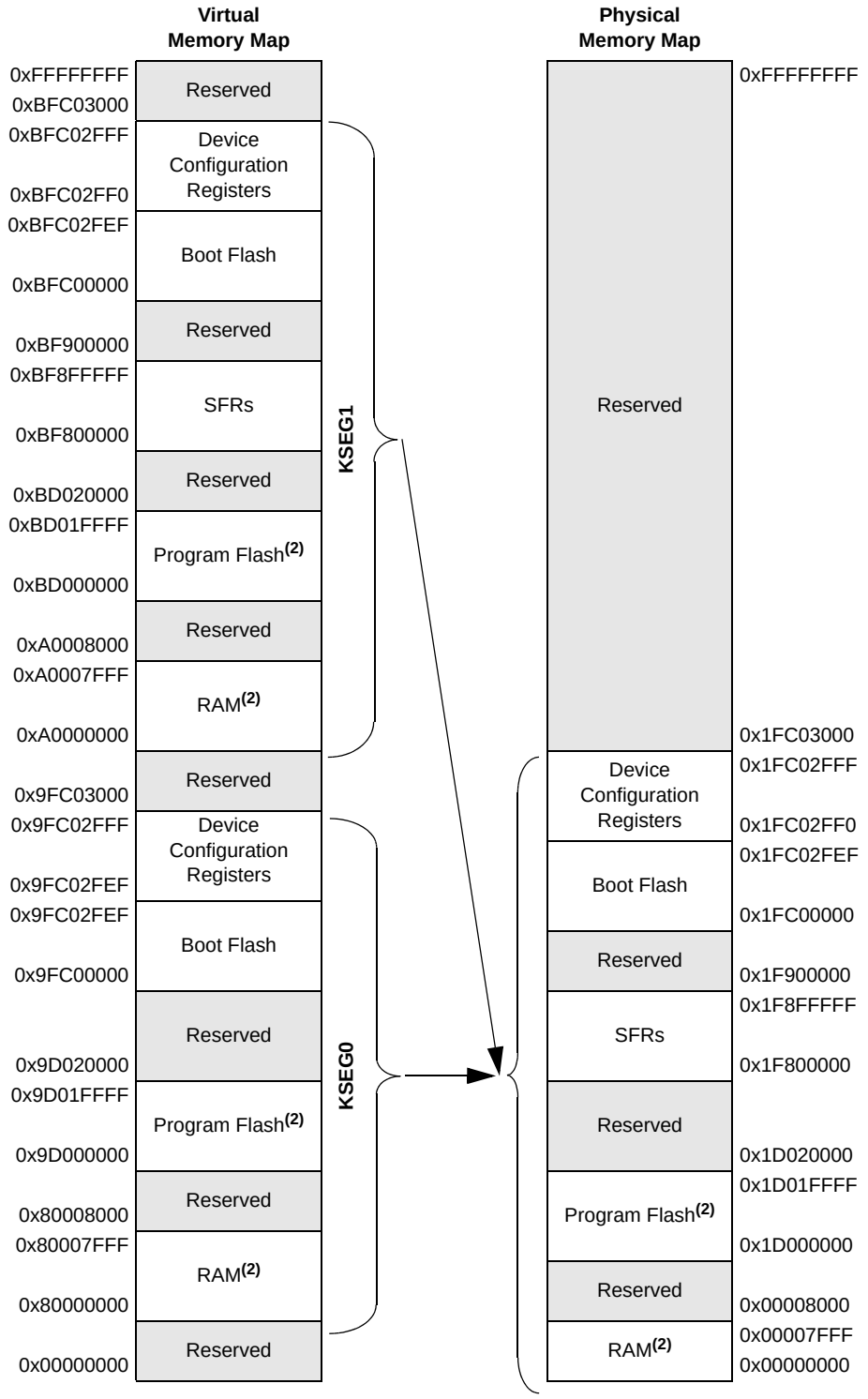
TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
TMS	23	17	G3	I	ST	JTAG Test mode select pin.
TCK	27	38	J6	I	ST	JTAG test clock input pin.
TDI	28	60	G11	I	ST	JTAG test data input pin.
TDO	24	61	G9	O	—	JTAG test data output pin.
RTCC	42	68	E9	O	—	Real-Time Clock Alarm Output.
CVREF-	15	28	L2	I	Analog	Comparator Voltage Reference (low).
CVREF+	16	29	K3	I	Analog	Comparator Voltage Reference (high).
CVREFOUT	23	34	L5	O	Analog	Comparator Voltage Reference Output.
C1IN-	12	21	H2	I	Analog	Comparator 1 Negative Input.
C1IN+	11	20	H1	I	Analog	Comparator 1 Positive Input.
C1OUT	21	32	K4	O	—	Comparator 1 Output.
C2IN-	14	23	J2	I	Analog	Comparator 2 Negative Input.
C2IN+	13	22	J1	I	Analog	Comparator 2 Positive Input.
C2OUT	22	33	L4	O	—	Comparator 2 Output.
PMA0	30	44	L8	I/O	TTL/ST	Parallel Master Port Address Bit 0 Input (Buffered Slave modes) and Output (Master modes).
PMA1	29	43	K7	I/O	TTL/ST	Parallel Master Port Address Bit 1 Input (Buffered Slave modes) and Output (Master modes).
PMA2	8	14	F3	O	—	Parallel Master Port Address (De-multiplexed Master Modes).
PMA3	6	12	F2	O	—	
PMA4	5	11	F4	O	—	
PMA5	4	10	E3	O	—	
PMA6	16	29	K3	O	—	
PMA7	22	28	L2	O	—	
PMA8	32	50	L11	O	—	
PMA9	31	49	L10	O	—	
PMA10	28	42	L7	O	—	
PMA11	27	41	J7	O	—	
PMA12	24	35	J5	O	—	
PMA13	23	34	L5	O	—	
PMA14	45	71	C11	O	—	
PMA15	44	70	D11	O	—	
PMCS1	45	71	C11	O	—	Parallel Master Port Chip Select 1 Strobe.
PMCS2	44	70	D11	O	—	Parallel Master Port Chip Select 2 Strobe.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX340F128H, PIC32MX340F128L, PIC32MX440F128H AND PIC32MX440F128L DEVICES(1)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS61115)) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

TABLE 4-13: ADC REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9000	AD1CON1(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	FORM<2:0>			SSRC<2:0>			CLRASAM	—	ASAM	SAMP	DONE	0000
9010	AD1CON2(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	VCFG2	VCFG1	VCFG0	OFFCAL	—	CSCNA	—	—	BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
9020	AD1CON3(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
9040	AD1CHS(1)	31:16	CH0NB	—	—	—	CH0SB<3:0>				CH0NA	—	—	—	CH0SA<3:0>				0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
9060	AD1PCFG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PCFG15	PCFG14	PCFG13	PCFG12	PCFG11	PCFG10	PCFG9	PCFG8	PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
9050	AD1CSSL(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CSSL15	CSSL14	CSSL13	CSSL12	CSSL11	CSSL10	CSSL9	CSSL8	CSSL7	CSSL6	CSSL5	CSSL4	CSSL3	CSSL2	CSSL1	CSSL0	0000
9070	ADC1BUF0	31:16	ADC Result Word 0 (ADC1BUF0<31:0>)																0000
		15:0																	0000
9080	ADC1BUF1	31:16	ADC Result Word 1 (ADC1BUF1<31:0>)																0000
		15:0																	0000
9090	ADC1BUF2	31:16	ADC Result Word 2 (ADC1BUF2<31:0>)																0000
		15:0																	0000
90A0	ADC1BUF3	31:16	ADC Result Word 3 (ADC1BUF3<31:0>)																0000
		15:0																	0000
90B0	ADC1BUF4	31:16	ADC Result Word 4 (ADC1BUF4<31:0>)																0000
		15:0																	0000
90C0	ADC1BUF5	31:16	ADC Result Word 5 (ADC1BUF5<31:0>)																0000
		15:0																	0000
90D0	ADC1BUF6	31:16	ADC Result Word 6 (ADC1BUF6<31:0>)																0000
		15:0																	0000
90E0	ADC1BUF7	31:16	ADC Result Word 7 (ADC1BUF7<31:0>)																0000
		15:0																	0000
90F0	ADC1BUF8	31:16	ADC Result Word 8 (ADC1BUF8<31:0>)																0000
		15:0																	0000
9100	ADC1BUF9	31:16	ADC Result Word 9 (ADC1BUF9<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-16: DMA CHANNELS 0-3 REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY(1) (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3160	DCH1DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3170	DCH1SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
3180	DCH1DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
3190	DCH1SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSPTR<7:0>								0000
31A0	DCH1DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDPTR<7:0>								0000
31B0	DCH1CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCSIZ<7:0>								0000
31C0	DCH1CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCPTR<7:0>								0000
31D0	DCH1DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
31E0	DCH2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
31F0	DCH2ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3200	DCH2INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3210	DCH2SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
3220	DCH2DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3230	DCH2SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
3240	DCH2DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
3250	DCH2SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSPTR<7:0>								0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers except DCHxSPTR, DCHxDPTR and DCHxCPTR have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-42: DEVICE AND REVISION ID SUMMARY

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F220	DEVID	31:16	VER<3:0>				DEVID<27:16>												xxxx
		15:0	DEVID<15:0>																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Program Memory"** (DS61121) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

PIC32MX3XX/4XX devices contain an internal program Flash memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self Programming (RTSP)
- In-Circuit Serial Programming™ (ICSP™)
- EJTAG Programming

RTSP is performed by software executing from either Flash or RAM memory. EJTAG is performed using the EJTAG port of the device and a EJTAG capable programmer. ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP. RTSP techniques are described in this chapter. The ICSP and EJTAG methods are described in the "*PIC32MX Flash Programming Specification*" (DS61145), which can be downloaded from the Microchip web site.

Note: Flash LVD Delay (LVDstartup) must be taken into account between setting up and executing any Flash command operation. See Example 5-1 for a code example to set up and execute a Flash command operation.

EXAMPLE 5-1:

```
NVMCON = 0x4004;          // Enable and configure for erase operation
Wait(delay);              // Delay for 6 µs for LVDstartup

NVMKEY = 0xAA996655;
NVMKEY = 0x556699AA;
NVMCONSET = 0x8000;       // Initiate operation

while(NVMCONbits.WR==1);  // Wait for current operation to complete
```

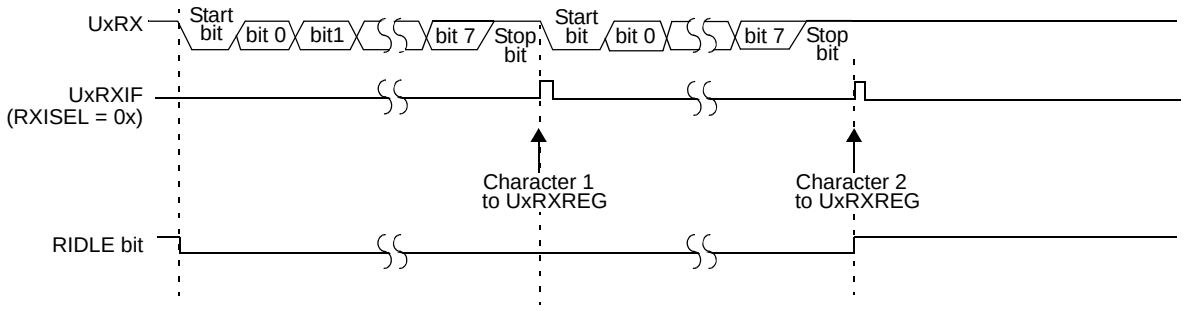
TABLE 7-1: INTERRUPT IRQ AND VECTOR LOCATION (CONTINUED)

Interrupt Source(1)	IRQ	Vector Number	Interrupt Bit Location			
Highest Natural Order Priority			Flag	Enable	Priority	Subpriority
SPI2E – SPI2 Fault	37	31	IFS1<5>	IEC1<5>	IPC7<28:26>	IPC7<25:24>
SPI2TX – SPI2 Transfer Done	38	31	IFS1<6>	IEC1<6>	IPC7<28:26>	IPC7<25:24>
SPI2RX – SPI2 Receive Done	39	31	IFS1<7>	IEC1<7>	IPC7<28:26>	IPC7<25:24>
U2E – UART2 Error	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>
U2RX – UART2 Receiver	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>
U2TX – UART2 Transmitter	42	32	IFS1<10>	IEC1<10>	IPC8<4:2>	IPC8<1:0>
I2C2B – I2C2 Bus Collision Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>
I2C2S – I2C2 Slave Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>
I2C2M – I2C2 Master Event	45	33	IFS1<13>	IEC1<13>	IPC8<12:10>	IPC8<9:8>
FSCM – Fail-Safe Clock Monitor	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>
RTCC – Real-Time Clock and Calendar	47	35	IFS1<15>	IEC1<15>	IPC8<28:26>	IPC8<25:24>
DMA0 – DMA Channel 0	48	36	IFS1<16>	IEC1<16>	IPC9<4:2>	IPC9<1:0>
DMA1 – DMA Channel 1	49	37	IFS1<17>	IEC1<17>	IPC9<12:10>	IPC9<9:8>
DMA2 – DMA Channel 2	50	38	IFS1<18>	IEC1<18>	IPC9<20:18>	IPC9<17:16>
DMA3 – DMA Channel 3	51	39	IFS1<19>	IEC1<19>	IPC9<28:26>	IPC9<25:24>
FCE – Flash Control Event	56	44	IFS1<24>	IEC1<24>	IPC11<4:2>	IPC11<1:0>
USB	57	45	IFS1<25>	IEC1<25>	IPC11<12:10>	IPC11<9:8>
Lowest Natural Order Priority						

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX General Purpose – Features"** and **TABLE 2: "PIC32MX USB – Features"** for available peripherals.

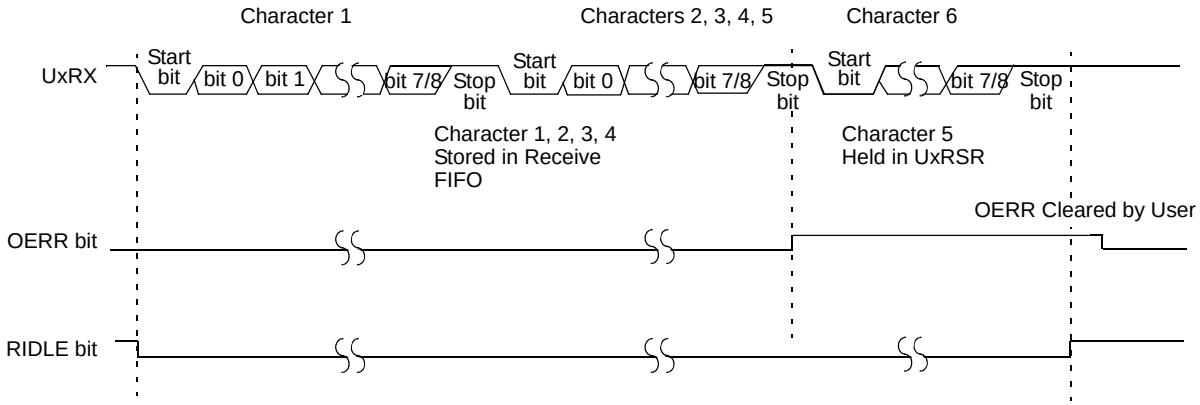
NOTES:

FIGURE 19-4: UART RECEPTION



Note: This timing diagram shows 2 characters received on the UxRX input.

FIGURE 19-5: UART RECEPTION WITH RECEIVE OVERRUN



Note: This diagram shows 6 characters received without the user reading the input buffer. The 5th character received is held in the Receive Shift register. An overrun error occurs at the start of the 6th character.

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
JAL	Jump and Link	GPR[31] = PC + 8 PC = PC[31:28] || offset<<2
JALR	Jump and Link Register	Rd = PC + 8 PC = Rs
JALR.HB	Jump and Link Register with Hazard Barrier	Like JALR, but also clears execution and instruction hazards
JR	Jump Register	PC = Rs
JR.HB	Jump Register with Hazard Barrier	Like JR, but also clears execution and instruction hazards
LB	Load Byte	Rt = (byte)Mem[Rs+offset]
LBU	Unsigned Load Byte	Rt = (ubyte))Mem[Rs+offset]
LH	Load Halfword	Rt = (half)Mem[Rs+offset]
LHU	Unsigned Load Halfword	Rt = (uhalf)Mem[Rs+offset]
LL	Load Linked Word	Rt = Mem[Rs+offset> LL_{bit} = 1 LLAdr = Rs + offset
LUI	Load Upper Immediate	Rt = immediate << 16
LW	Load Word	Rt = Mem[Rs+offset]
LWPC	Load Word, PC relative	Rt = Mem[PC+offset]
LWL	Load Word Left	Re = Re MERGE Mem[Rs+offset]
LWR	Load Word Right	Re = Re MERGE Mem[Rs+offset]
MADD	Multiply-Add	HI | LO += (int)Rs * (int)Rt
MADDU	Multiply-Add Unsigned	HI | LO += (uns)Rs * (uns)Rt
MFC0	Move from Coprocessor 0	Rt = CPR[0, Rd, sel]
MFHI	Move from HI	Rd = HI
MFLO	Move from LO	Rd = LO
MOVN	Move Conditional on Not Zero	if Rt ¼ 0 then Rd = Rs
MOVZ	Move Conditional on Zero	if Rt = 0 then Rd = Rs
MSUB	Multiply-Subtract	HI | LO -= (int)Rs * (int)Rt
MSUBU	Multiply-Subtract Unsigned	HI | LO -= (uns)Rs * (uns)Rt
MTC0	Move to Coprocessor 0	CPR[0, n, Sel] = Rt
MTHI	Move to HI	HI = Rs
MTLO	Move to LO	LO = Rs
MUL	Multiply with register write	HI | LO =Unpredictable Rd = ((int)Rs * (int)$Rt)_{31..0}$
MULT	Integer Multiply	HI | LO = (int)Rs * (int)Rd
MULTU	Unsigned Multiply	HI | LO = (uns)Rs * (uns)Rd
NOP	No Operation (Assembler idiom for: SLL r0, r0, r0)	
NOR	Logical NOR	Rd = ~(Rs | Rt)
OR	Logical OR	Rd = Rs | Rt
ORI	Logical OR Immediate	Rt = Rs | Immed
RDHWR	Read Hardware Register (if enabled by $HWRE_{na}$ Register)	Re = HWR[Rd]

Note 1: This instruction is deprecated and should not be used.

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
RDPGPR	Read GPR from Previous Shadow Set	Rt = SGPR[$SRSCtl_{PSS}$, Rd]
ROTR	Rotate Word Right	Rd = $Rt_{sa-1..0}$ || $Rt_{31..sa}$
ROTRV	Rotate Word Right Variable	Rd = $Rt_{Rs-1..0}$ || $Rt_{31..Rs}$
SB	Store Byte	(byte)Mem[Rs+offset] = Rt
SC	Store Conditional Word	if LL_{bit} = 1 mem[Rs+offset> = Rt Rt = LL_{bit}
SDBBP	Software Debug Break Point	Trap to SW Debug Handler
SEB	Sign-Extend Byte	Rd = SignExtend (Rs-7...0)
SEH	Sign-Extend Half	Rd = SignExtend (Rs-15...0)
SH	Store Half	(half)Mem[Rs+offset> = Rt
SLL	Shift Left Logical	Rd = Rt << sa
SLLV	Shift Left Logical Variable	Rd = Rt << Rs[4:0]

SLT	Set on Less Than	if (int)Rs < (int)Rt
		Rd = 1
		else
		Rd = 0

SLTI	Set on Less Than Immediate	if (int)Rs < (int)Immed
		Rt = 1
		else
		Rt = 0

SLTIU	Set on Less Than Immediate Unsigned	if (uns)Rs < (uns)Immed
		Rt = 1
		else
		Rt = 0

SLTU	Set on Less Than Unsigned	if (uns)Rs < (uns)Immed
		Rd = 1
		else
		Rd = 0

SRA	Shift Right Arithmetic	Rd = (int)Rt >> sa
SRAV	Shift Right Arithmetic Variable	Rd = (int)Rt >> Rs[4:0]
SRL	Shift Right Logical	Rd = (uns)Rt >> sa
SRLV	Shift Right Logical Variable	Rd = (uns)Rt >> Rs[4:0]
SSNOP	Superscalar Inhibit No Operation	NOP
SUB	Integer Subtract	Rt = (int)Rs - (int)Rd
SUBU	Unsigned Subtract	Rt = (uns)Rs - (uns)Rd
SW	Store Word	Mem[Rs+offset] = Rt
SWL	Store Word Left	Mem[Rs+offset] = Rt
SWR	Store Word Right	Mem[Rs+offset] = Rt
SYNC	Synchronize	Orders the cached coherent and uncached loads and stores for access to the shared memory
SYSCALL	System Call	SystemCallException
TEQ	Trap if Equal	if Rs == Rt TrapException
TEQI	Trap if Equal Immediate	if Rs == (int)Immed TrapException

Note 1: This instruction is deprecated and should not be used.

28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY(3)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	1000	—	—	E/W	—
D131	VPR	VDD for Read	VMIN	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	3.0	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	—
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	20	—	40	µs	—
D136	TRW	Row Write Cycle Time(2) (128 words per row)	3	4.5	—	ms	—
D137	TPE	Page Erase Cycle Time	20	—	—	ms	—
	TCE	Chip Erase Cycle Time	80	—	—	ms	—
D138	LVDstartup	Flash LVD Delay	—	—	6	µs	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the "*PIC32MX Flash Programming Specification*" (DS61145) for operating conditions during programming and erase cycles.

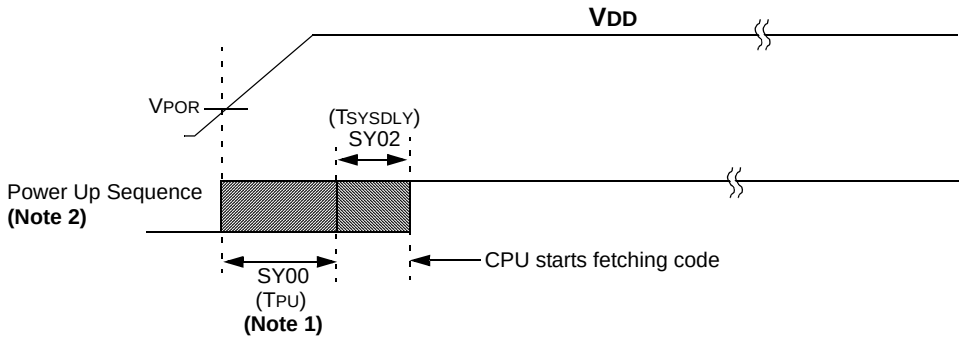
TABLE 29-12: PROGRAM FLASH MEMORY WAIT STATE CHARACTERISTICS

DC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp		
Required Flash wait states	**SYSCLK**	**Units**	**Comments**
0 Wait State	0 to 30	MHz	—
1 Wait State	31 to 60		
2 Wait States	61 to 80		

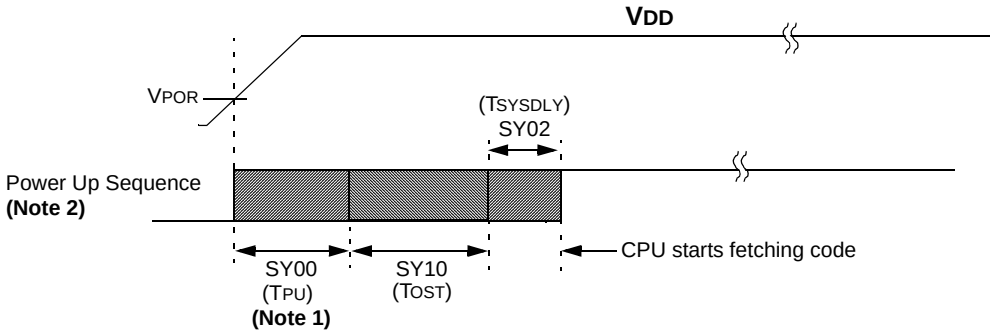
Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

FIGURE 29-4: POWER-ON RESET TIMING CHARACTERISTICS

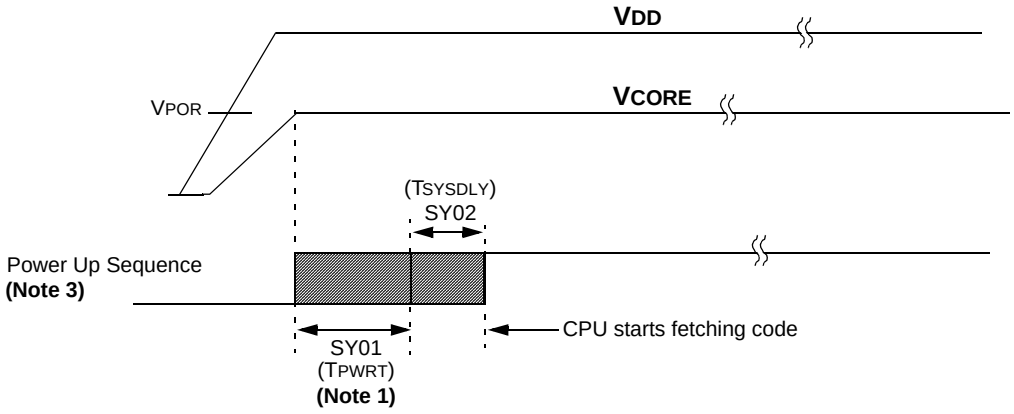
Internal Voltage Regulator Enabled
Clock Sources = (FRC, FRCDIV, FRCDIV16, FRCPLL, EC, ECPLL and LPRC)



Internal Voltage Regulator Enabled
Clock Sources = (HS, HSPLL, XT, XTPLL and SOSC)



External VCORE Provided
Clock Sources = (FRC, FRCDIV, FRCDIV16, FRCPLL, EC, ECPLL and LPRC)

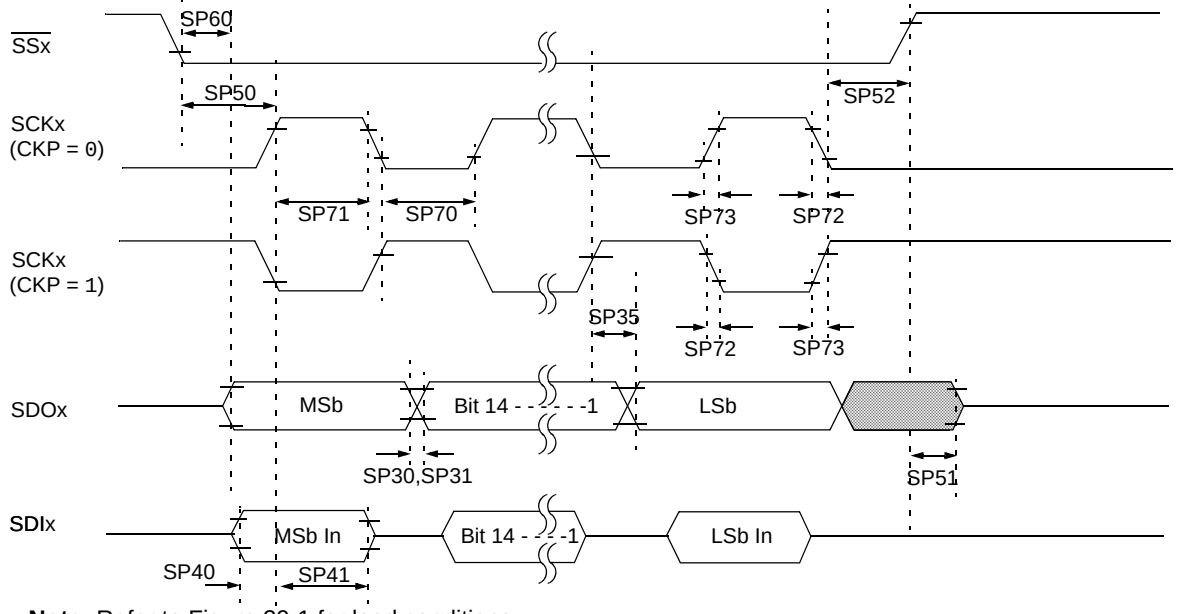


Note 1: The Power-up period will be extended if the power-up sequence completes before the device exits from BOR (VDD < VDDMIN).

2: Includes interval voltage regulator stabilization delay.

3: Power-up Timer (PWRT); only active when the internal voltage regulator is disabled.

FIGURE 29-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time(3)	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time(3)	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TscR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TdoF	SDOx Data Output Fall Time(4)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(4)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓to SCKx ↓or SCKx ↑ Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(4)	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	Tsck + 20	—	—	ns	—
SP60	TssL2doV	$\overline{SDOx}$ Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE A-3: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 "Electrical Characteristics"	Added the new V-Temp temperature range (-40ºC to +105ºC) to the heading of all specification tables. Updated the Ambient temperature under bias, updated the Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V, and added Voltage on VBUS with respect to Vss in Absolute Maximum Ratings. Added the characteristic, DC5a to Operating MIPS vs. Voltage (see Table 29-1). Updated or added the following parameters to the Operating Current (IDD) DC Characteristics: DC20, DC23, DC24c, DC25d, DC26c (see Table 29-5). Added the following parameters to the Idle Current (IIDLE) DC Characteristics: DC30c, DC31c, DC32c, DS33c, DC34c, DC35c, and DC36c (see Table 29-6). Added the following parameters to the Power-down Current (IPD) DC Characteristics: DC40g, DC40h, DC40i, DC41g, DC41h, DC42g, DC42h, DC42i, DC43h, and DC43i (see Table 29-7). Added the Brown-out Reset (BOR) Electrical Characteristics (see Table 29-10). Removed all Conditions from the Program Memory DC Characteristics (see Table 29-11). Removed the AC Characteristics voltage reference table (Table 29-15). Added Note 2 to the PLL Clock Timing Specifications (see Table 29-18). Updated the OC/PWM Module Timing Characteristics (see Figure 29-9). Added parameter IM51 and Note 3 to the I2Cx Bus Data Timing Requirements (Master Mode) (see Table 29-32). Added parameter numbers (AD13, AD14, and AD15) to the ADC Module Specifications (see Table 29-34). Updated the 10-bit ADC Conversion Rate Parameters (see Table 29-35). Updated parameter AD57 (TSAMP) in the Analog-to-Digital Conversion Timing Requirements (see Table 29-36). Updated the Conditions for parameters USB313, USB318, and USB319 in the OTG Electrical Specifications (see Table 29-40).
Section 30.0 "Packaging Information"	Updated the 64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] packing diagram.
Product Identification System	Added the new V-Temp (V) temperature information.